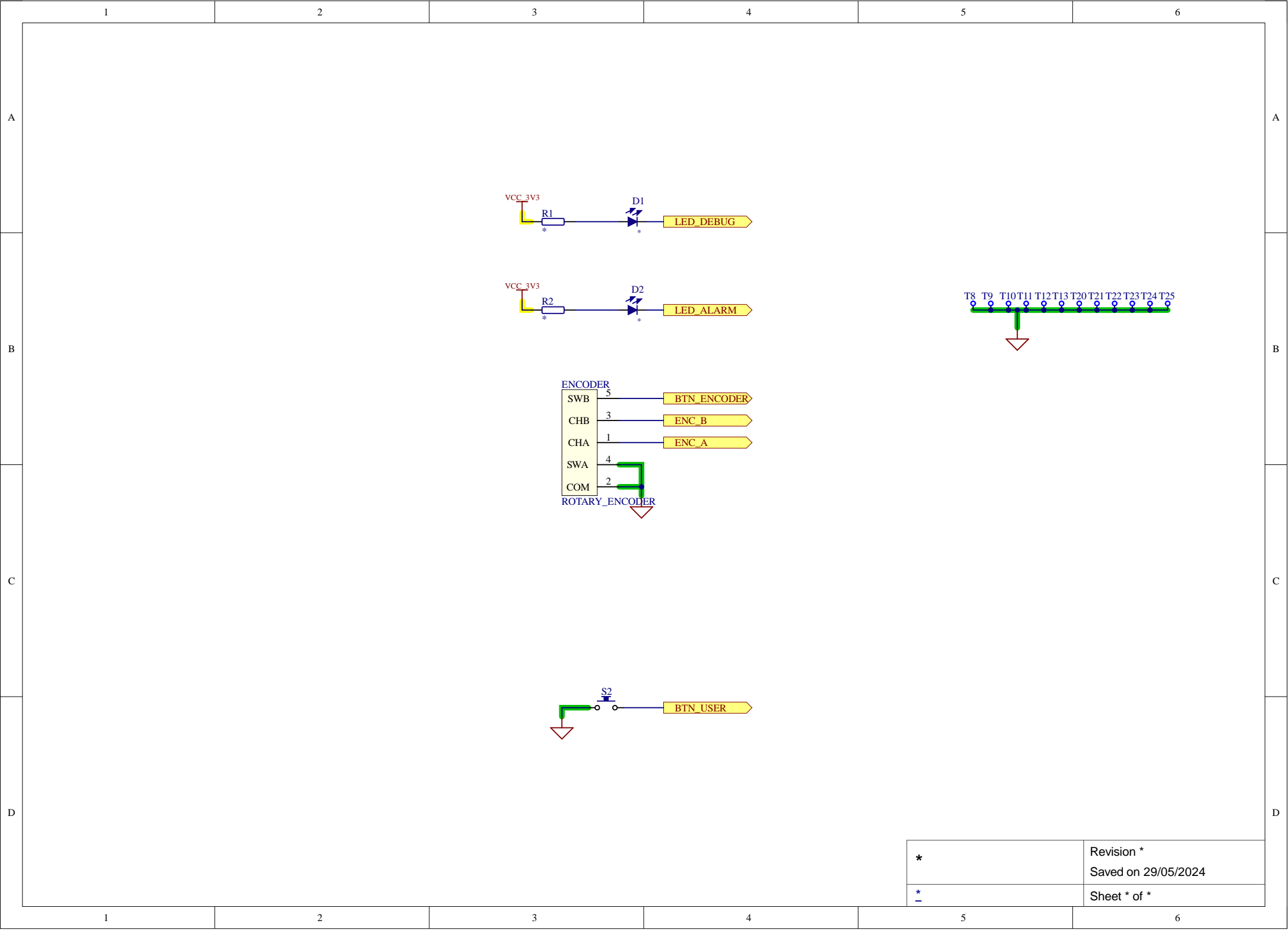


1	2	3	4	5	6
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Design Rules Verification Report

Filename : E:\dev\wifi_alarm_clock\pcbs\devkit\alarm_clock_devkit\alarm_clock_devkit.Prj

Warnings 0
Rule Violations 0

Warnings	
Total	0

Rule Violations	
Clearance Constraint (Gap=20mil) (InNetClass('POWER24') And ((IsPad And (InNet('GND') Or InNet('VCC_LED'))))	0
Clearance Constraint (Gap=-3.937mil) (InPadClass('AGND_TIE')), (InNet('GND') And OnBottomLayer	0
Clearance Constraint (Gap=5mil) (All), (All)	0
Clearance Constraint (Gap=7.874mil) (All), (IsKeepOut	0
Short-Circuit Constraint (Allowed=No) (All), (All)	0
Short-Circuit Constraint (Allowed=Yes) (InPadClass('AGND_TIE')), (InNet('GND')	0
Un-Routed Net Constraint (All)	0
Modified Polygon (Allow modified: No), (Allow shelved: No)	0
Width Constraint (Min=5mil) (Max=50mil) (Preferred=5mil) (All)	0
Routing Layers(All)	0
Routing Via (Templates Used To Check Via: GND_VIA, POWER_VIA) (All	0
Power Plane Connect Rule(Relief Connect)(Expansion=20mil) (Conductor Width=5mil) (Air Gap=5mil) (Entries=4) (Al	0
Minimum Annular Ring (Minimum=5.118mil) (IsPad,	0
Minimum Annular Ring (Minimum=5.118mil) (IsVia,	0
Acute Angle Constraint [Tracks Only] (Minimum=45.000) (All,	0
Hole Size Constraint (Min=11.811mil) (Max=118.11mil) (All,	0
Hole To Hole Clearance (Gap=7.874mil) (All), (All,	0
Minimum Solder Mask Sliver (Gap=3.937mil) (All), (All,	0
Net Antennae (Tolerance=0mil) (All)	0
Board Clearance Constraint (Gap=0mil) (InLayerClass('Electrical Layers')	0
Component Clearance Constraint (Horizontal Gap = 3.937mil, Vertical Gap = Infinite) (All), (All)	0
Component Clearance Constraint (Horizontal Gap = 0mil, Vertical Gap = 0mil) (All), (InComponentClass('TestPoint')	0
Height Constraint (Min=0mil) (Max=1000mil) (Preferred=500mil) (All,	0
Total	0

U1

J2

R8

T15

T17

T18

T19

T14

T16

J3

R11

C26

R9

C9

R10

C8

R3

R1

R2

D1

D2

J4

ENCODER

S2

IC2

C2

C1

C25

C3

T26

R7

C20

C11

R4

C14

C21

Y1

C24

C22

C15

C13

C23

C12

C16

C17

C19

C18

L

C7

C4

C5

U3

U

R

IC1

M1

D3

D4




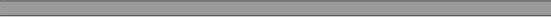






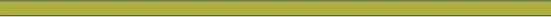
R5

D5

T27

J1

Board Stack Report

Stack Up		Layer Stack			
Layer	Board Layer Stack	Name	Material	Thickness	Constant
1		Top Paste			
2		Top Overlay			
3		Top Solder	SM-001	0.025mm	4
4		Top Layer	Copper	0.035mm	
5		Dielectric 2	PP-006	0.210mm	4.1
6		Layer 1	Copper	0.015mm	
7		Dielectric 1	Core-043	1.065mm	4.3
8		Layer 2	Copper	0.015mm	
9		Dielectric 3	PP-006	0.210mm	4.1
10		Bottom Layer	Copper	0.035mm	
11		Bottom Solder	SM-001	0.025mm	4
12		Bottom Overlay			
13		Bottom Paste			
Height : 1.637mm					